SURFACE MOUNTING INTEGRATED CIRCUIT COMPONENTS

Abstract of the Disclosure

An electronic apparatus may include a first component solder bonded to a second component. The first component may be, for example, an integrated circuit. The first component may have an array of metallic protrusions. Those protrusions may be coupled to circuit elements within said first component. The second component may include a plurality of solder portions coupled to the second component and engaged by the protrusions on the first component in a soldered connection.

(Fig. 1)